Thermal Management Solutions

Technical Data Sheet



TCSG3000 Thermal Conductive Silicone Gel

Product Description

TCSG3000 is an excellent thermal conductive silicone gel, which can easily fit and adhere to most shapes and sizes of components, and the thermal conductivity is high as 3.0W/m•K. TCSG3000 can provide extremely low thermal impedance when at thin bondline thickness.

Features

- Dispensable pre-cured gel and easy for application
- Soft and easily fit and adhere to components
- Extremely high thermal conductivity: 3.0W/m-K
- · Low thermal resistance
- Low minimum bond line thickness
- No pump-out
- Natural tacky surface and reworkable
- · Long-term using and storage stability
- RoHS Compliant

Approvals

RoHS Compliant Yes

Typical Applications

- · Microprocessors/Graphics Processors
- Automotive Electronic Control Units(ECU's)
- Telecom Device
- Wireless hub
- Memory & Power Modules
- Power Supplies and Semiconductors
- Consumer electronics

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Typical Properties

Color: Gray Specific Gravity: 3.2

Flow rate@ 30cc taper tip, 0.100"orifice, 90psi: 60 grams/min

Typical Minimum Bond Line Thickness 0.035mm
Thermal Conductivity: 3.0 W/mK

Flammability Rating: UL 94 V-0
Operation Temperature Range: -50~200 °C
Dielectric Strength: 8 kV/mm

Volume Resistivity: 1.0*10¹⁴ Ohm-

cm

Storage

Store from 5° C to 35° C with a maximum humidity of 50%. Do not store in a freezer.